Unit: mm

TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOSIV)

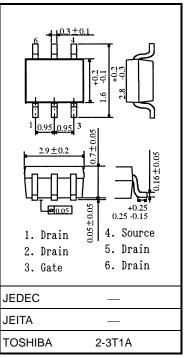
TPC6107

Notebook PC Applications Portable Equipment Applications

- · Small footprint due to small and thin package
- Low drain-source ON resistance: RDS (ON) = 40 m Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 9.6 \text{ S (typ.)}$
- Low leakage current: $IDSS = -10 \mu A (max) (VDS = -20 V)$
- Enhancement model: V_{th} = -0.5 to -1.2 V $(V_{DS}$ = -10 V, I_{D} = -200 $\mu A)$

Absolute Maximum Ratings (Ta = 25°C)

Characteris	etics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	-20	V	
Drain-gate voltage (R _G	_S = 20 kΩ)	V_{DGR}	-20	V	
Gate-source voltage		V_{GSS}	±12	V	
Drain current	DC (Note 1)	I _D	-4.5	А	
Diam current	Pulse (Note 1)	I _{DP}	-18		
Drain power dissipation	(t = 5 s) (Note 2a)	P _D	2.2	W	
Drain power dissipation	(t = 5 s) (Note 2b)	P _D	0.7	W	
Single pulse avalanche	energy (Note 3)	E _{AS}	1.3	mJ	
Avalanche current		I _{AR}	-2.25	А	
Repetitive avalanche e	nergy (Note 4)	E _{AR}	0.22	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature ra	nge	T _{stg}	-55 to 150	°C	



Weight: 0.011 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

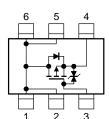
Thermal Characteristics

Characteristics	Symbol	Max	Unit	
Thermal resistance, channel to ambient (t = 5 s) (Note 2a)	R _{th (ch-a)}	56.8	°C/W	
Thermal resistance, channel to ambient (t = 5 s) (Note 2b)	R _{th (ch-a)}	178.5	°C/W	

Note: (Note 1), (Note 2), (Note 3), (Note 4) and (Note 5): See the next page.

This transistor is an electrostatic-sensitive device. Please handle with caution.

Circuit Configuration



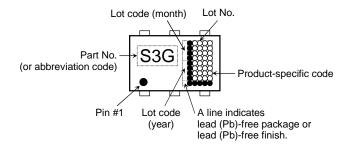
Electrical Characteristics (Ta = 25°C)

Ch	aracteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cui	rrent	I _{GSS}	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0 \text{ V}$	_		±10	μА
Drain cut-OFF cu	urrent	I _{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	-10	μА
Drain-source breakdown voltage		V (BR) DSS	$I_D = -10$ mA, $V_{GS} = 0$ V	-20			V
		V (BR) DSX	$I_D = -10 \text{ mA}, V_{GS} = 12 \text{ V}$	-8	_	_	
Gate threshold v	oltage	V _{th}	$V_{DS} = -10 \text{ V}, I_D = -200 \mu\text{A}$	-0.5	_	-1.2	V
Drain-source ON resistance		R _{DS} (ON)	$V_{GS} = -2 \text{ V}, I_D = -2.2 \text{ A}$	_	110	180	mΩ
		R _{DS} (ON)	$V_{GS} = -2.5 \text{ V}, I_D = -2.2 \text{ A}$	_	70	100	
		R _{DS} (ON)	$V_{GS} = -4.5 \text{ V}, I_D = -2.2 \text{ A}$	_	40	55	
Forward transfer	admittance	Y _{fs}	$V_{DS} = -10 \text{ V}, I_D = -2.2 \text{ A}$	4.8	9.6	_	S
Input capacitance		C _{iss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz	_	680	_	pF
Reverse transfer capacitance		C _{rss}		_	130	_	
Output capacitance		C _{oss}		_	140	_	
Switching time	Rise time	t _r	V _{GS} 0 V I _D = -2.2 A C _G C	_	6	_	
	Turn-ON time	ton		_	16	_	
	Fall time	tf		_	38	_	ns
	Turn-OFF time	t _{off}	$V_{DD} \simeq -10 \text{ V}$ Duty ≤ 1%, $t_W = 10 \text{ μs}$	_	85	_	
Total gate charge (gate-source plus gate-drain)		Qg	V _{DD} ≃ −16 V, V _{GS} = −5 V, I _D = −4.5 A	_	9.8	_	
Gate-source charge		Q _{gs}		_	2	_	nC
Gate-drain ("miller") charge		Q _{gd}		_	3	_	

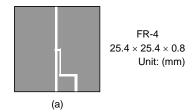
Source-Drain Ratings and Characteristics (Ta = 25°C)

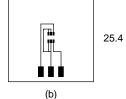
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Pulse drain reverse current	(Note 1)	I _{DRP}	_	_	_	-18	Α
Forward voltage (diode)		V_{DSF}	$I_{DR} = -4.5 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V

Marking (Note 5)



- Note 1: Ensure that the channel temperature does not exceed 150°C.
- Note 2: (a) Device mounted on a glass-epoxy board (a) (t = 5 s)
 - (b) Device mounted on a glass-epoxy board (b) (t = 5 s)

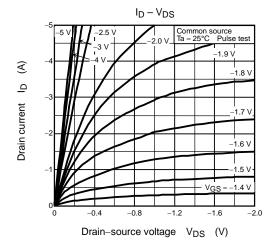


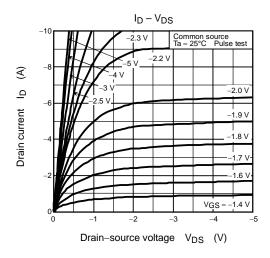


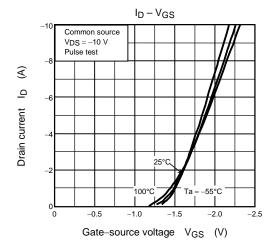
 $\begin{aligned} & \text{FR-4} \\ 25.4 \times 25.4 \times 0.8 \\ & \text{Unit: (mm)} \end{aligned}$

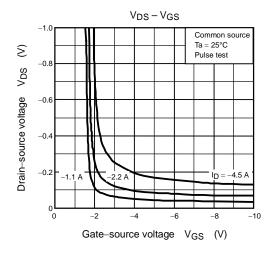
- Note 3: V_{DD} = 16 V, T_{Ch} = 25°C (initial), L = 0.2 mH, R_G = 25 Ω , I_{AR} = -2.25 A
- Note 4: Repetitive rating: pulse width limited by maximum channel temperature
- Note 5: on lower left of the marking indicates Pin 1.

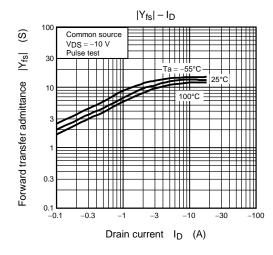
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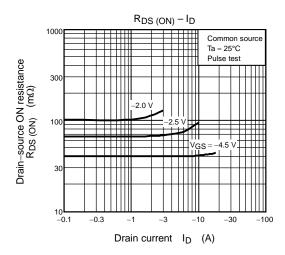


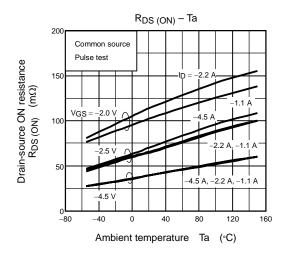


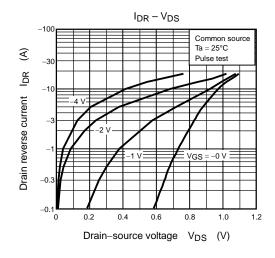


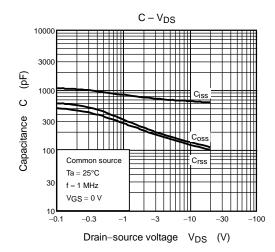


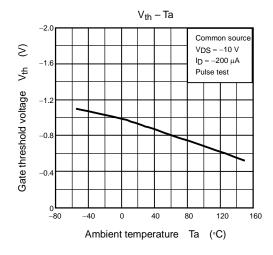


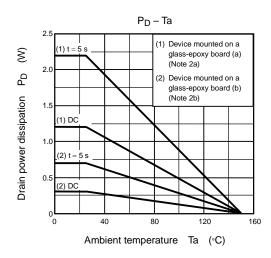


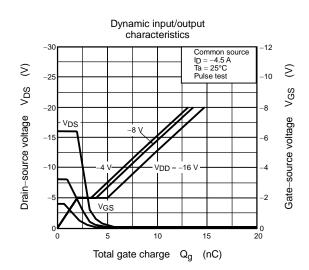


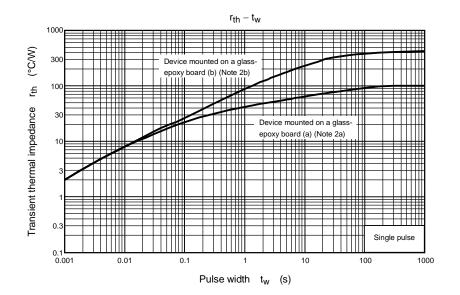


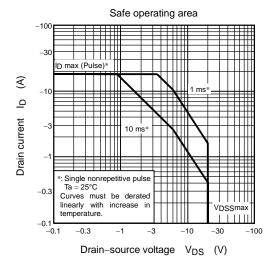












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